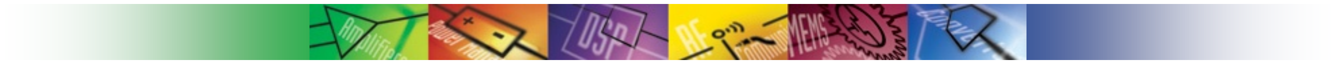

Product / Package Information

Package	LFCSP - Punch
Body Size (mm)	5 X 5 X 0.85 (2.7 EP)
LeadCount	32
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
JIG Material Content Compliant	Level A & B Compliant
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.34E-02	86.9	869100	36.20	361968
Thermosets	Epoxy & Phenol Resin	Proprietary	3.45E-03	12.8	127800	5.32	53227
Other inorganic materials	Carbon black	1333-86-4	8.36E-05	0.3	3100	0.13	1291
Subtotal			2.70 E-02	100.00	1000000	41.65	416487

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	3.18 E-02	97.5	975000	49.14	491413
Copper & its alloys	Iron	7439-89-6	7.67 E-04	2.35	23500	1.18	11844
Copper & its alloys	Zinc	7440-66-6	3.92 E-05	0.12	1200	0.06	605
Copper & its alloys	Phosphorus	7723-14-0	9.80 E-06	0.03	300	0.02	151
Subtotal			3.27 E-02	100.00	1000000	50.40	504014

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.10 E-04	100.0	1000000	0.94	9416

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	9.50 E-04	100.0	1000000	1.47	14665

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.40 E-04	100.0	1000000	1.30	12967

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.13 E-03	100.0	1000000	3.29	32881

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.55 E-04	73.40	734000	0.70	7025
Thermoset	Epoxy Resin	Proprietary	1.14 E-04	18.35	183500	0.18	1756
Other inorganic materials	Metal oxide	Proprietary	1.71 E-05	2.75	27500	0.03	263
Others	Curing and hardening agent	Proprietary	1.71 E-05	2.75	27500	0.03	263
Other organic materials	Gamma Butyrolactone	96-48-0	1.71 E-05	2.75	27500	0.03	263
Subtotal			6.20 E-04	100.0	1000000	0.96	9571

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.48 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES